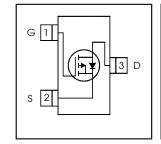
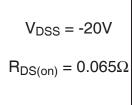


- Ultra Low On-Resistance
- P-Channel MOSFET
- SOT-23 Footprint
- Low Profile (<1.1mm)
- Available in Tape and Reel
- Fast Switching
- Lead-Free
- Halogen-Free





Description

These P-Channel MOSFETs from International Rectifier utilize advanced processing techniques to achieve extremely low onresistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET® power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in battery and load management.

A thermally enhanced large pad leadframe has been incorporated into the standard SOT-23 package to produce a HEXFET Power MOSFET with the industry's smallest footprint. This package, dubbed the Micro3™, is ideal for applications where printed circuit board space is at a premium. The low profile (<1.1mm) of the Micro3 allows it to fit easily into extremely thin application environments such as portable electronics and PCMCIA cards. The thermal resistance and power dissipation are the best available.



Absolute Maximum Ratings

	Parameter	Max.	Units	
V _{DS}	Drain- Source Voltage	-20	V	
$I_D @ T_A = 25^{\circ}C$	Continuous Drain Current, V _{GS} @ -4.5V	-3.7		
I _D @ T _A = 70°C	Continuous Drain Current, V _{GS} @ -4.5V	-2.2	Α	
I _{DM}	Pulsed Drain Current ①	-22		
P _D @T _A = 25°C	Power Dissipation	1.3	· w	
P _D @T _A = 70°C	Power Dissipation	0.8	_ vv	
	Linear Derating Factor	0.01	W/°C	
E _{AS}	Single Pulse Avalanche Energy®	11	mJ	
V_{GS}	Gate-to-Source Voltage	± 12	V	
T _J , T _{STG}	Junction and Storage Temperature Range	-55 to + 150	°C	

Thermal Resistance

	Parameter	Тур.	Max.	Units
$R_{\theta JA}$	Maximum Junction-to-Ambient®	75	100	°C/W



Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	-20			V	$V_{GS} = 0V, I_D = -250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient		-0.009		V/°C	Reference to 25°C, I _D = -1mA ②
B	Static Drain-to-Source On-Resistance		0.050	0.065	0	V _{GS} = -4.5V, I _D = -3.7A ②
R _{DS(on)}	Static Drain to Source Off resistance		0.080	0.135	Ω	V _{GS} = -2.5V, I _D = -3.1A ②
V _{GS(th)}	Gate Threshold Voltage	-0.40	-0.55	-1.2	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
9 _{fs}	Forward Transconductance	6.0			S	V _{DS} = -10V, I _D = -3.7A ②
1	Drain-to-Source Leakage Current			-1.0		V _{DS} = -20V, V _{GS} = 0V
I _{DSS}	Diali-to-Source Leakage Current			-25	μA	$V_{DS} = -20V, V_{GS} = 0V, T_{J} = 70^{\circ}C$
I _{GSS}	Gate-to-Source Forward Leakage			-100	nA	V _{GS} = -12V
IGSS	Gate-to-Source Reverse Leakage			100	11/4	V _{GS} = 12V
Q_g	Total Gate Charge		8.0	12		I _D = -3.7A
Q _{gs}	Gate-to-Source Charge		1.2	1.8	nC	$V_{DS} = -10V$
Q_{gd}	Gate-to-Drain ("Miller") Charge		2.8	4.2		V _{GS} = -5.0V ②
t _{d(on)}	Turn-On Delay Time		350			V _{DD} = -10V
t _r	Rise Time		48		ns	$I_D = -3.7A$
t _{d(off)}	Turn-Off Delay Time		588		115	$R_G = 89\Omega$
t _f	Fall Time		381			$R_D = 2.7\Omega$
C _{iss}	Input Capacitance		633			V _{GS} = 0V
Coss	Output Capacitance		145		pF	$V_{DS} = -10V$
C _{rss}	Reverse Transfer Capacitance		110			f = 1.0MHz

Source-Drain Ratings and Characteristics

	Parameter	Min.	Тур.	Max.	Units	Conditions				
Is	Continuous Source Current	Source Current	1.0	MOSFET symbol						
	(Body Diode)			1.3	-1.3	-1.3	-1.3	-1.3	Α	showing the
I _{SM}	Pulsed Source Current			00	00		integral reverse			
	(Body Diode) ①	y Diode) ①	-22		p-n junction diode.					
V _{SD}	Diode Forward Voltage			-1.2	V	$T_J = 25^{\circ}C$, $I_S = -1.0A$, $V_{GS} = 0V$ ②				
t _{rr}	Reverse Recovery Time		29	43	ns	$T_J = 25^{\circ}C, I_F = -1.0A$				
Q _{rr}	Reverse RecoveryCharge		11	17	nC	di/dt = -100A/µs ②				

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width \leq 400 μ s; duty cycle \leq 2%.
- ③ Surface mounted on 1" square single layer 1oz. copper FR4 board, steady state.